

Product Data Sheet

Product	S62-325GM5
Productgroup	Solder Paste Dispense
Date	21-01-2011
Release	06.2

5	Especially made for this purpose
4	Generally qualified for this purpose
3	Generally usable, but not the best choice
2	Generally not usable for this purpose
1	Wrong choice

ISO 9454-1	1.2.2.C
JIS Z3284	1.2.3.N.I
IPC-ANSI-J-STD-004	REL1
IPC-ANSI-J-STD-005 (Powder)	4.
No-Clean process	5
Post-solder cleaning	3
Pb-Free process - Air, Standard	1
Pb-Free process - Air, Extended	1
Pb-Free process - N2	1
Vapor Phase	3
Consumer electronics	4
Med-Rel electronics	4
Hi-Rel electronics	5
OSP compatible	5
Ni/Au compatibel	5
Ni/Pd compatible	4
Ag compatible	4
Sn compatible	4
Automatic Hi-Speed Dispensing	5
Manual Dispensing	3
Fine-pitch (=< 0.625 mm)	5
Reduces solder balling	5
Reduces solder beading	4
Reduces bridging	4
Reduces tombstoning	4
Reduces de-wetting	5
Brilliant joint appearance	5
Cosmetic cleanliness	4
Reduces flux build-up in reflow oven	4
ICCT compatible	4
Conformal coating	5

Flux code	325.GM5
Particle size code	H
Alloy code	Sn62
Alloy type	Sn62/Pb36/Ag2
Liquidus [°C]	179.
Solidus [°C]	179.
Recommended peak temp. [°C]	205-225
Particle size [m]	25-38
Oxide content powder [ppm]	100.
Acid number [mgKOH] (+/-2.5%)	49.30
Halides [Silver-Chromate Test]	Pass
Halides [Potentiometric]	Detected
Flux [% w/w]	13.50
Metal [% w/w]	86.50
Filmformer(s)	Resin
Color of the residue	Colorless
Viscosity @25 °C [Pa's] Plate/Plate (+/-18%)	74.
Viscosity @ 25°C [Pa's] Malcom PCU205 (+/-18%)	64.
Min. Needle Diameter [swg]	26.
Minimum Dot	
Size [mm]	< 65
Dwell [m/sec]	50.
Maximum Dot	
Tackiness time 20°C/ 70%RH [H]	12.
Tackiness force Malcom TK1 [gr]	75.
Telcordia/Bellcore TR-NWT-000078/3	Compliant
IPC/ANSI-J-STD-005	Compliant
Test report(s)	-
Certificate of Compliance	Available
SPC-data*	Auditable
Environmental Load Unit	4.32
RoHS-Compliance Certificate	Not available
User's Guidelines	English
Packaging	
Jar (PP) [gram]	500
Small cartridge (HDPE) [gram]	650
Large cartridge (HDPE) [gram]	1300
Syringe (HDPE) [gram]	25, 75
Shelf-life (Weeks)	
Storage 4-10 [°C]	26.
Storage 20 [°C]	13.